

**IN SITU APPLICATION OF ETCH BACK FOR IMPROVED DEPOSITION  
INTO HIGH-ASPECT-RATIO FEATURES**

**ABSTRACT OF THE DISCLOSURE**

5                   A continuous *in situ* process of deposition, etching, and deposition is  
provided for forming a film on a substrate using a plasma process. The etch-back may  
be performed without separate plasma activation of the etchant gas. The sequence of  
deposition, etching, and deposition permits features with high aspect ratios to be filled,  
while the continuity of the process results in improved uniformity.

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